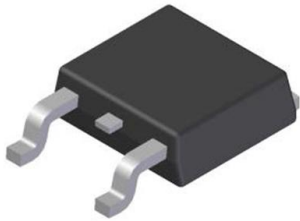


ZXMN10A11KTC Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	ZXMN10A11KTC-DG
Manufacturer	Diodes Incorporated
Manufacturer Product Number	ZXMN10A11KTC
Description	MOSFET N-CH 100V 2.4A TO252-2
Detailed Description	N-Channel 100 V 2.4A (Ta) 2.11W (Ta) Surface Mount TO-252-3



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

ZXMN10A11KTC

Series:

-

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

100 V

Drive Voltage (Max Rds On, Min Rds On):

6V, 10V

Vgs(th) (Max) @ Id:

4V @ 250µA

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-252-3

Base Product Number:

ZXMN10

Manufacturer:

Diodes Incorporated

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

2.4A (Ta)

Rds On (Max) @ Id, Vgs:

350mOhm @ 2.6A, 10V

Gate Charge (Qg) (Max) @ Vgs:

5.4 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

274 pF @ 50 V

Power Dissipation (Max):

2.11W (Ta)

Mounting Type:

Surface Mount

Package / Case:

TO-252-3, DPAK (2 Leads + Tab), SC-63

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

ZXMN10A11K

100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ\text{C}$
100V	350m Ω @ $V_{GS} = 10\text{V}$	3.5A
	450m Ω @ $V_{GS} = 6\text{V}$	3.1A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

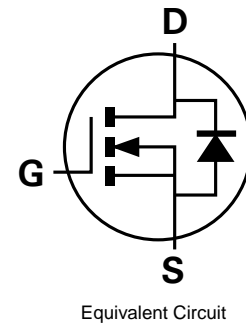
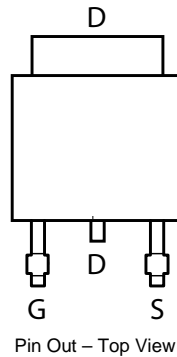
- Motor control
- DC-DC Converters
- Power management functions
- Uninterrupted power supply

Features and Benefits

- Fast switching speed
- Low input capacitance
- “Green” Component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TO252-3L
- Case Material: Molded Plastic “Green” Molding Compound, UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.33 grams (approximate)

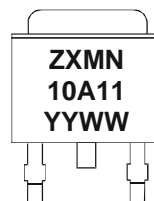


Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN10A11KTC	See Below	13	16	2,500

Note: 1. Diodes, Inc. defines “Green” products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.’s “Green” Policy can be found on our website. For packaging details, go to our website.

Marking Information



ZXMN = Product Type Marking Code, Line 1
 10A11 = Product Type Marking Code, Line 2
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01-52)


ZXMN10A11K
Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V_{DSS}	100	V	
Gate-Source voltage			V_{GS}	± 20	V	
Continuous Drain current	$V_{GS} = 10\text{V}$	(Note 3)	I_D	3.5	A	
		$T_A = 70^\circ\text{C}$ (Note 3)		2.8		
		(Note 2)		2.4		
Pulsed Drain current	$V_{GS} = 10\text{V}$	(Note 4)	I_{DM}	9.9	A	
Continuous Source current (Body diode)			(Note 3)	I_S	8.4	A
Pulsed Source current (Body diode)			(Note 4)	I_{SM}	9.9	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

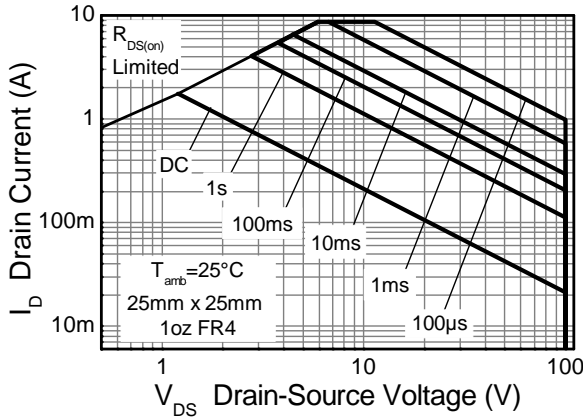
Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Note 2)	P_D	4.06	W mW/ $^\circ\text{C}$
			32.4	
	(Note 3)		8.5	
	(Note 6)		68.0	
Thermal Resistance, Junction to Ambient	(Note 2)	$R_{\theta JA}$	2.11	$^\circ\text{C/W}$
	(Note 3)		16.8	
	(Note 6)		30.8	
Thermal Resistance, Junction to Lead	(Note 2)	$R_{\theta JL}$	14.7	$^\circ\text{C/W}$
	(Note 3)		59.1	
	(Note 6)		1.10	
Operating and storage temperature range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

- Notes:
2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 3. Same as note 2, except the device is measured at $t \leq 10$ sec.
 4. Same as note 2, except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
 5. Thermal resistance from junction to solder-point (at the end of the drain lead).
 6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with the high coverage single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

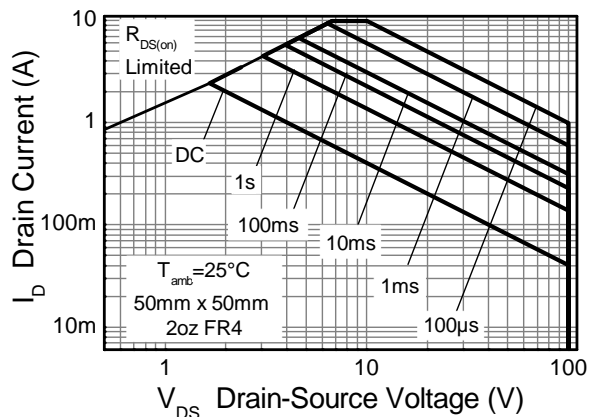


ZXMN10A11K

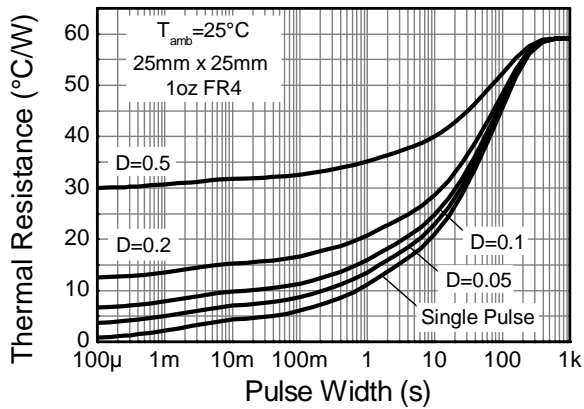
Thermal Characteristics



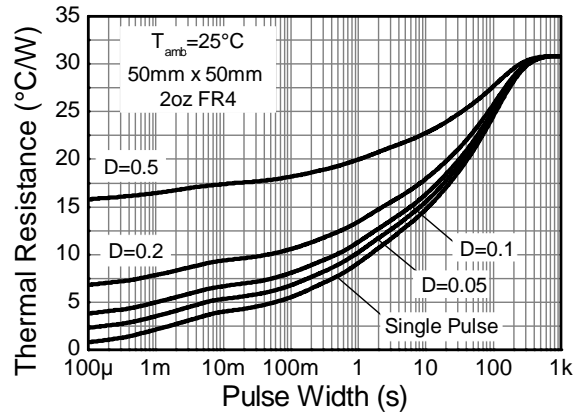
Safe Operating Area



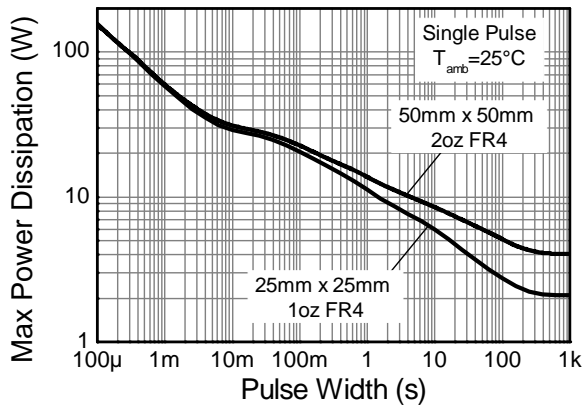
Safe Operating Area



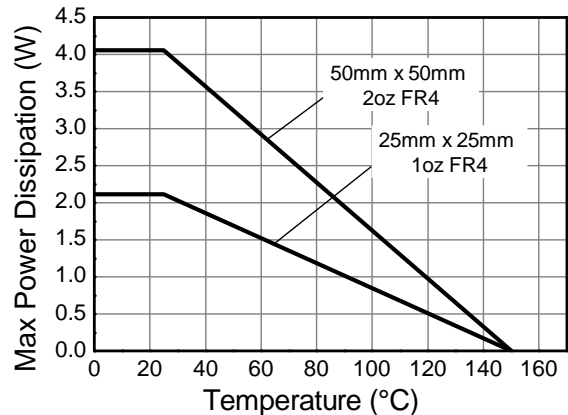
Transient Thermal Impedance



Transient Thermal Impedance



Pulse Power Dissipation



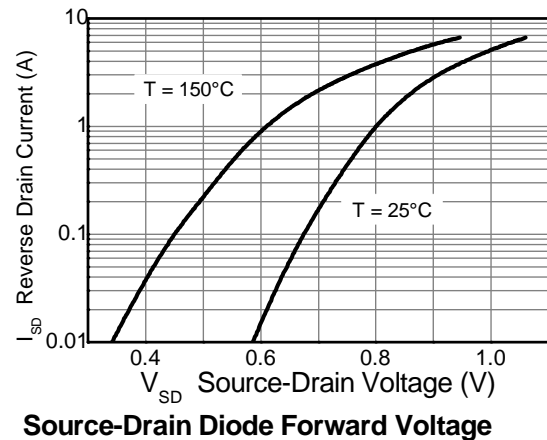
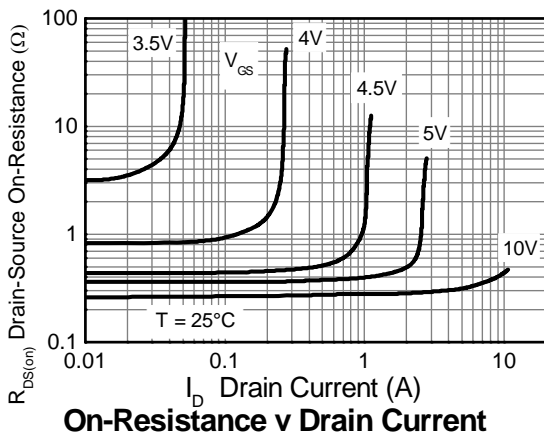
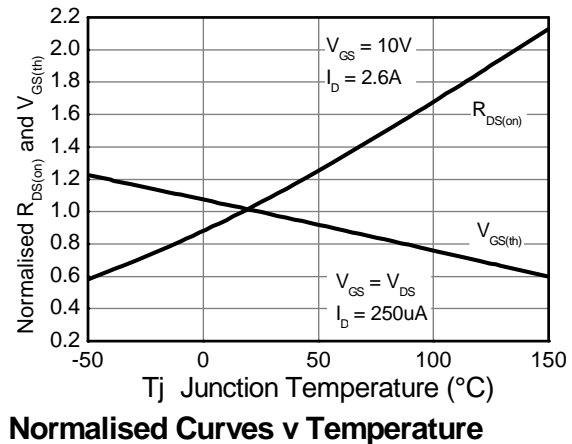
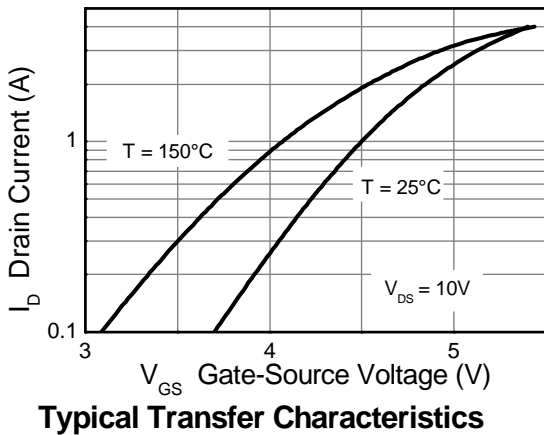
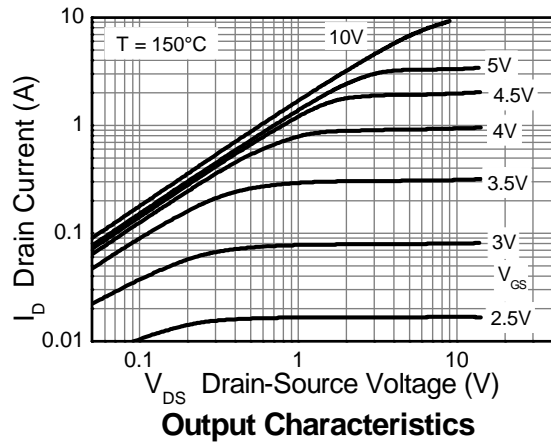
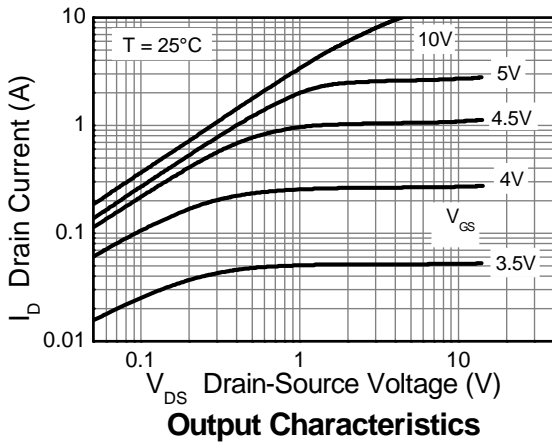
Derating Curve


ZXMN10A11K
Electrical Characteristics @T_A = 25°C unless otherwise specified

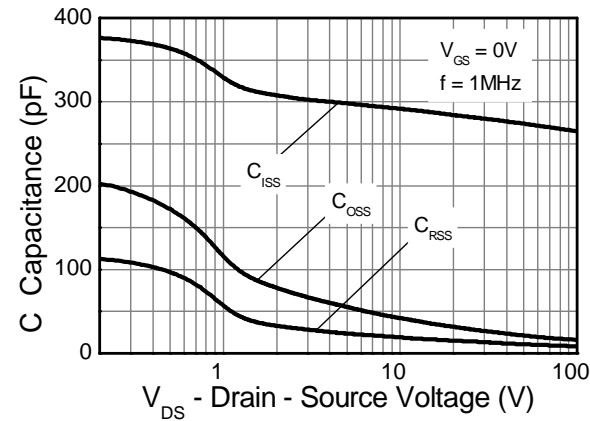
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 100V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	2	—	4	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 7)	R _{DS(on)}	—	—	0.350	Ω	V _{GS} = 10V, I _D = 2.6A
				0.450		V _{GS} = 6V, I _D = 1.3A
Forward Transconductance (Notes 7 & 8)	g _{fs}	—	4	—	S	V _{DS} = 15V, I _D = 2.6A
Diode Forward Voltage (Note 7)	V _{SD}	—	0.850	0.950	V	I _S = 1.85A, V _{GS} = 0V
Reverse recovery time (Note 8)	t _{rr}	—	26	—	ns	I _S = 1.0A, di/dt = 100A/μs
Reverse recovery charge (Note 8)	Q _{rr}	—	30	—	nC	
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	274	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	21	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	11	—	pF	
Total Gate Charge (Note 9)	Q _g	—	3.5	—	nC	V _{GS} = 6V
Total Gate Charge (Note 9)	Q _g	—	5.4	—	nC	V _{GS} = 10V
Gate-Source Charge (Note 9)	Q _{gs}	—	1.4	—	nC	
Gate-Drain Charge (Note 9)	Q _{gd}	—	1.5	—	nC	
Turn-On Delay Time (Note 9)	t _{D(on)}	—	2.7	—	ns	V _{DD} = 50V, V _{GS} = 10V I _D = 1.0A, R _G ≅ 6Ω
Turn-On Rise Time (Note 9)	t _r	—	1.7	—	ns	
Turn-Off Delay Time (Note 9)	t _{D(off)}	—	7.4	—	ns	
Turn-Off Fall Time (Note 9)	t _f	—	3.5	—	ns	

- Notes:
7. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
 8. For design aid only, not subject to production testing.
 9. Switching characteristics are independent of operating junction temperatures.

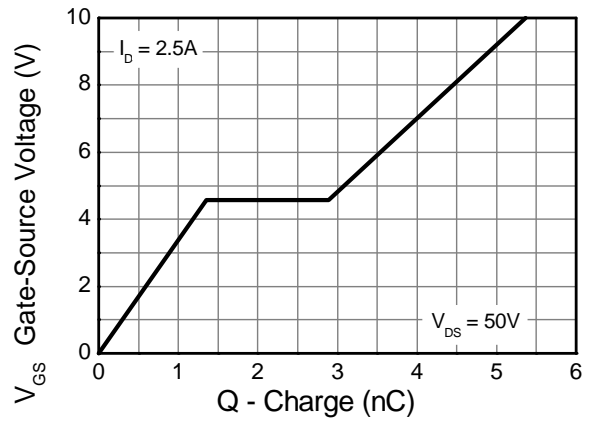
Typical Characteristics



Typical Characteristics - continued

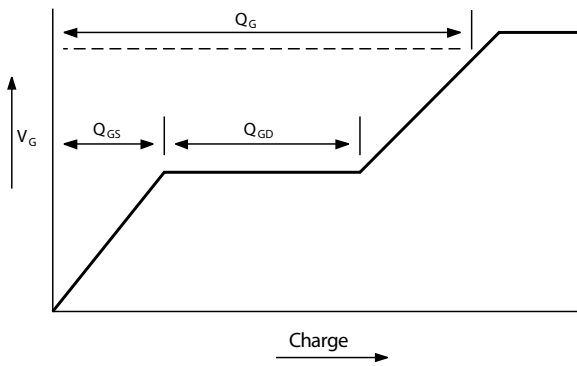


Capacitance v Drain-Source Voltage

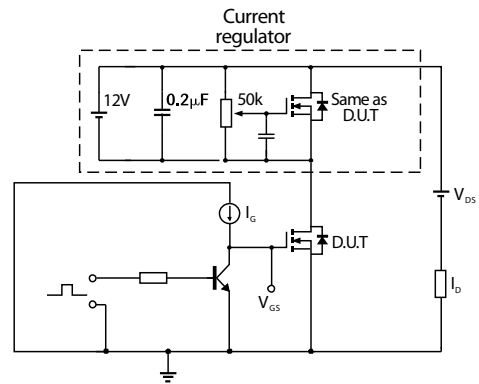


Gate-Source Voltage v Gate Charge

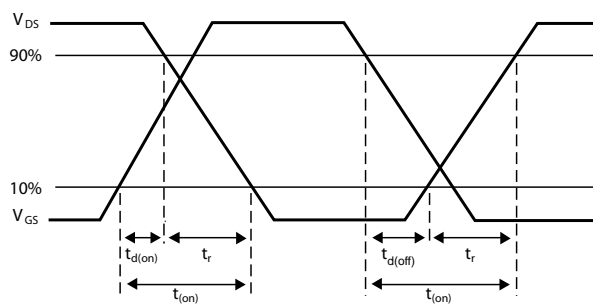
Test Circuits



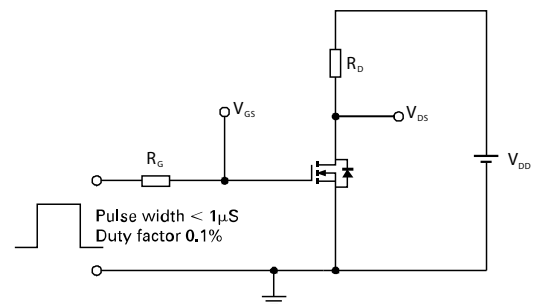
Basic gate charge waveform



Gate charge test circuit



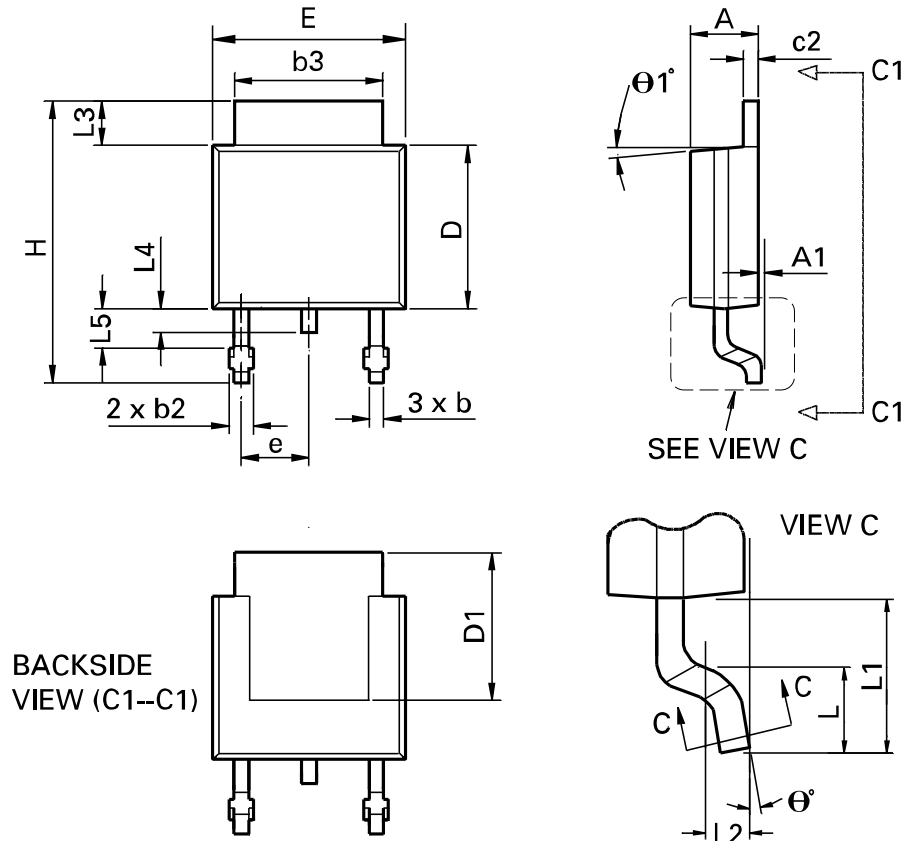
Switching time waveforms



Switching time test circuit

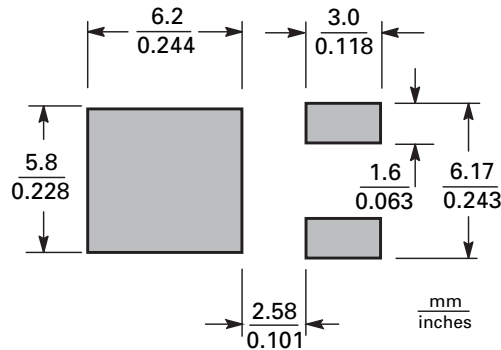
ZXMN10A11K

Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ_1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Suggested Pad Layout



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